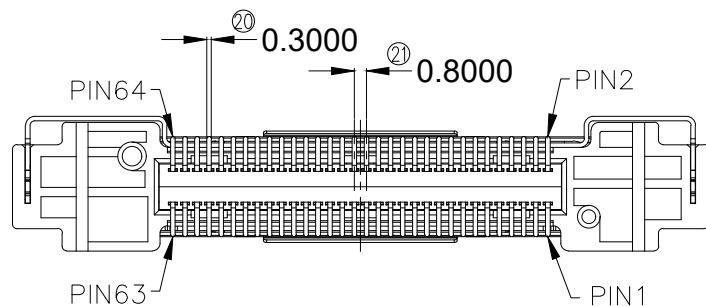
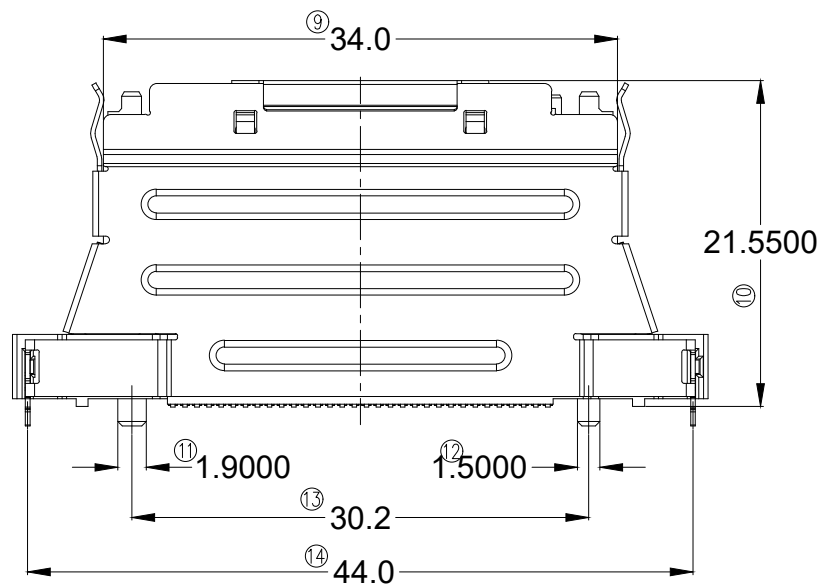
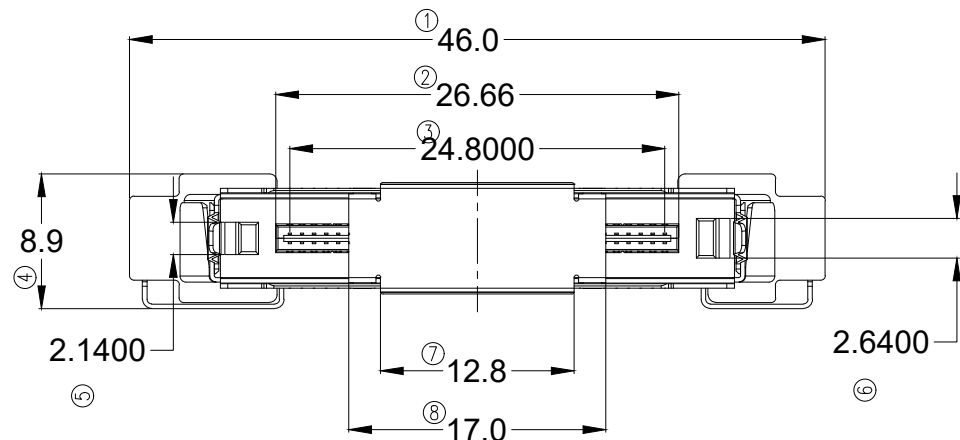


PROPRIETARY INFORMATION
COMPANY CONFIDENTIAL



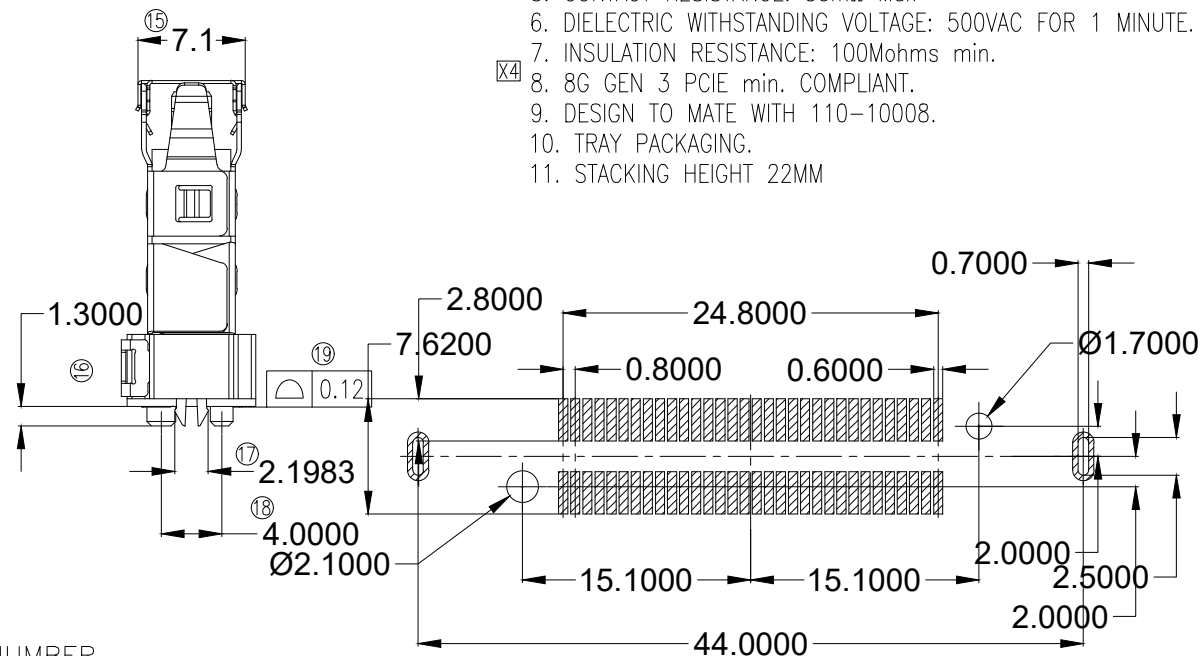
PART. NUMBER
110-10040-0X

- 01: GOLD FLASH PLATING
02: 4u" Au PLATING

REV.	ECN. NO.	DESCRIPTION	ENG	DATE
X1		INITIAL	Ryan	11/15/2018
X2		ADD NOTE	YIN	2/14/2019
X3		ADD SPEC	Leo	8/13/2020
X4		CHANGED THE 5G TO 8G	ZAKK	6/16/2023

NOTES :

- MATERIAL
HOUSING: LCP, UL94V-0, BLACK
TERMINAL: BRASS
SHIELD: SPTE
- PLATING:
TERMINAL:
CONTACT AREA: GOLD FLASH PLATING
SOLDER TAIL: 80u" TIN PLATING
UNDER PLATING: 30u" NICKEL OVERALL
- CURRENT RATING: 0.5A
- VOLTAGE RATING: 30V DC Max
- CONTACT RESISTANCE: 50mΩ Max
- DIELECTRIC WITHSTANDING VOLTAGE: 500VAC FOR 1 MINUTE.
- INSULATION RESISTANCE: 100Mohms min.
- 8G GEN 3 PCIE min. COMPLIANT.
- DESIGN TO MATE WITH 110-10008.
- TRAY PACKAGING.
- STACKING HEIGHT 22MM



RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05mm

GENERAL TOLERANCE X ± 0.50 .X ± 0.40 .XX ± 0.30 .XXX ± 0.20		ANGLE TOLERANCE X° ± 5.0° .X° ± 3.0° .XX° ± 2.0° .XXX° ± 1.0°		DRAWN Ryan		DATE 11/15/18'				
MATL FINISH SCALE <i>N/A</i> SHEET 1 OF 1				CHECKED YIN	DATE 11/15/18'		TITLE. HI-STACK B TO B 8Gbps MALE INTERFACE			
				APPROVED Terry	DATE 11/15/18'		PART NUMBER. 110-10040-01		DRAWING NO. 110-10040	
						SIZE <i>A4</i>		REV. <i>X4</i>		